

PATENT APPLICATION

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IN THE U.S. PATENT AND TRADEMARK OFFICE

April 14, 2006

Applicants : Atsushi YABE et al
For : ELECTROLESS COPPER PLATING SOLUTION AND
ELECTROLESS COPPER PLATING METHOD

PCT International Application No.: PCT/JP2004/014049
PCT International Filing Date: September 17, 2004
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Mail Stop PCT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

AMENDMENT BEFORE FIRST OFFICE ACTION

Sir:

Prior to issuance of the first Office Action in the
above-identified application, kindly enter the following:

(Please see following pages.)